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Atty. Docket No. CPAC 1017-3
Appl. No. 10/632,568

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Kurnezos

Application No.: 10/632,568

Filed: August 2, 2003

Title: Semiconductor multi-package module
having package stacked over ball grid array
package and having wire bond interconnect
between stacked packages

Examiner: Douglas M. Menz

Group Art Unit: 2824

Date: December 12, 2005.

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Signed

Paula Faulk Hurley

COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Final Office action mailed August 10, 2005, kindly amend the
application as follows.

Amendments to the claims are reflected in the Listing of Claims, which begins on page 2 of this
paper.

Remarks begin on page 6 of this paper.